

规格书编号

SPEC NO:

产品规格书 SPECIFICATION

CUSTOMER 客户:						
PRODUCT 产品:	SAW FILTER					
MODEL NO 型 号:	HDF458CF11					
PREPARED 编 制:	CHECKED 审 核:					
APPROVED 批准:	DATE日期	2006-5-11				
客户确认 CUSTOMER RECEIVED:						
审核 CHECKED	批准 APPROVED	日期 DATE				

无锡市好达电子有限公司 Shoulder Electronics Limited





更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark



1. SCOPE

SAW FILTER

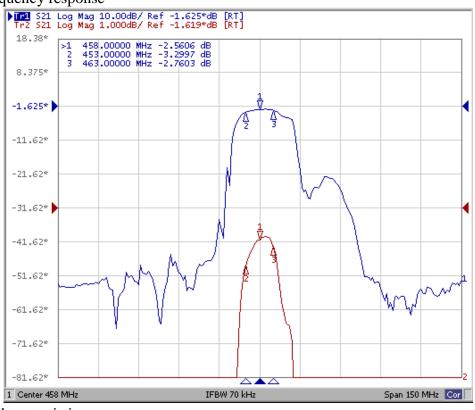
This specification shall cover the characteristics of SAW filter With F458C used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V		
AC Voltage Vpp	10V50Hz/60Hz		
Operation temperature	-40°C to +85°C		
Storage temperature	-45°C to +85°C		
RF Power Dissipation	0dBm		

Electronic Characteristics

2-1. Typical frequency response



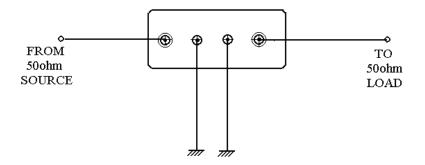
2-2. Electrical characteristics

Part number	F458C	Unit
Nominal center frequency (Fo)	458	MHz
Insertion Loss		
1.fo-45.8~fo-39.8 MHz	45min.	dB
$2.\text{fo}\pm5.0\text{MHz}$	5.0max.	
3.fo +39.8~ fo +45.8MHz	45min.	
Ripple (with Fo ± 3.0 MHz)	2.0max	dB
Input/Output Impedance(Nominal)	50//0	Ω/pF

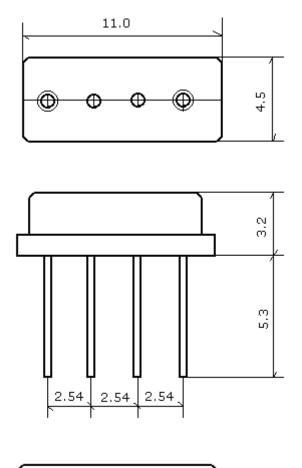


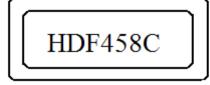
SAW FILTER HDF458CF11

3.TEST CIRCUIT



4. DIMENSION





5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a



SAW FILTER HDF458CF11

high temperature of $+25^{\circ}$ C for 5 Minutes and a higher temperature of $+85^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.